



Designation: E 1161 – 9503

An American National Standard

Standard Test Method for Radiologic Examination of Semiconductors and Electronic Components¹

This standard is issued under the fixed designation E 1161; the number immediately following the designation indicates the year of original adoption or, in the case of revision, the year of last revision. A number in parentheses indicates the year of last reapproval. A superscript epsilon (ε) indicates an editorial change since the last revision or reapproval.

1. Scope

1.1 This test method provides a standard procedure for nondestructive radiographic examination of semiconductor devices, electronic components, and the materials used for construction of these items. This test method covers the radiographic ~~testing~~ examination of these items for possible defective conditions such as extraneous material within the sealed case, improper internal connections, voids in materials used for element mounting, or the sealing glass, or physical damage.

1.2 The quality level and acceptance criteria for the specimens being ~~tested~~ examined shall be specified in the detail drawing, purchase order or contract.

1.3 *This standard does not purport to address all of the safety concerns, if any, associated with its use. It is the responsibility of the user of this standard to establish appropriate safety and health practices and determine the applicability of regulatory limitations prior to use.*

2. Referenced Documents

2.1 *ASTM Standards:*

¹ This test method is under the jurisdiction of ASTM Committee E-7 E07 on Nondestructive Testing and is the direct responsibility of Subcommittee E07.01 on Radiographic Practice Radiology (X and Penetrators-Gamma) Methods.

Current edition approved Dec. 10, 1995; 2003. Published February 1996; August 2003. Originally published as E 1161 – 87; approved in 1987. Last previous edition approved in 1995 as E 1161 – 925.